

### **In the Specification**

Please change the title to "Contact For Semiconductor Components".

On page 2, line 1, add the following:

### **--Cross Reference To Related Applications**

This application is a continuation of Serial No. 10/198,895 filed 07/18/2002, which is a division of Serial No. 09/275,791 filed 03/25/1999, Patent No. 6,437,591 B1.

This application is related to Serial No. 09/834,805 filed 04/12/2001.--

In the paragraph on page 25, line 25, to page 26, line 2, please make the following change.

--The test carrier 80 includes the interconnect 10A, and a force applying mechanism 82. The interconnect 10A includes contacts ~~14D~~ 14 adapted to make temporary electrical connections with the bumped contacts 16 on the components 18A. The contacts 14 can be formed as previously described for contacts 14A (Figures 2A), or contacts 14B (Figure 5A), or contacts 14C (Figure 4A), or contacts 14D (Figure 4C). In addition, the interconnect 10A includes conductive vias 32 in electrical communication with the contacts 14. The conductive vias 32 can be formed as previously described for conductive vias 32A (Figure 2D).--